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(54) MULTIPLE-CHAMBER APPARATUS HAVING WAFER-ID READING FUNCTION

(57) Abstract:

PURPOSE: To provide a multiple-chamber apparatus having the wafer-ID reading function, which can automatically control the setting of the processing conditions of wafers to be processed and the progressing state.

CONSTITUTION: This apparatus is used in the semiconductor manufacturing process, wherein wafers are sequentially inserted into a plurality of process chambers and the processing is performed in the integrated pattern. The multiple-chamber apparatus does not have a docking chamber. Four process chambers 2-5, a wafer loader chamber 6 and a wafer unloader chamber 7 are connected to a wafer conveying chamber 1. These chambers are controlled with a control system 8. Wafer-ID reading parts 2a-7a and the like, which read the wafer ID of a wafer 9, respectively, are provided in the process chambers 2-5, the wafer loader chamber 6 and the wafer unloader chamber 7. The wafer ID, which is marked at the specified position on the wafer 9, is optically read when the wafer 9 is conveyed in and out.

